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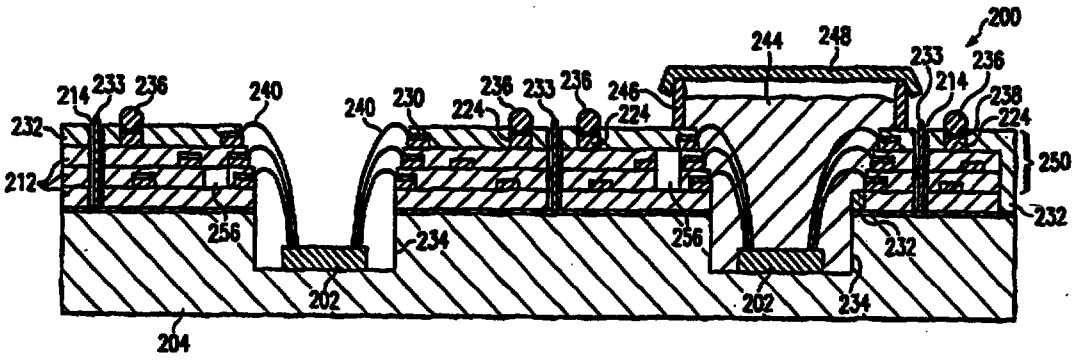
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(54) Title: SEQUENTIALLY BUILT INTEGRATED CIRCUIT PACKAGE



(57) Abstract

An enhanced ball grid array substrate package and method for manufacturing the same, where the substrate package includes a metal core (204) having a first surface and a second surface opposite the first surface. The metal core further includes at least one cavity in which at least one integrated circuit (202) is positioned. A dielectric layer is secured to the first surface of the metal core and includes at least one die cavity formed therein. Thereafter, a conductive seed layer (218) is chemically deposited to exposed portion of the dielectric layer and the first suface of the meal core. Adjacent to the conductive seed layer, a circuit is electrolytically and selectively formed within a first circuit pattern.